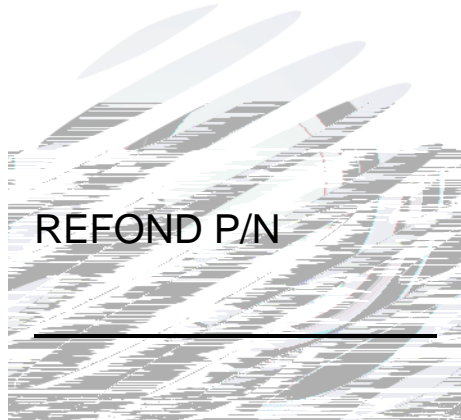


# SPECIFICATION



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## 1. Description

### 1.1 General Description



This production has a high reliability, good heat dissipation, are widely used in the disinfection, uv sterilization, Air purification, etc.

### 1.2 Features

Size(mm):3.5\*3.5\*1.5.

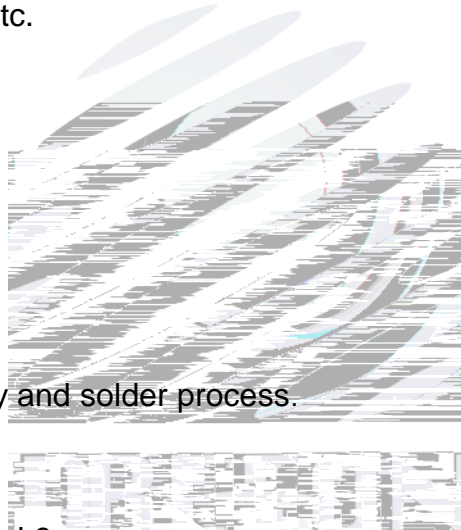
Viewing angle:120° .

Suitable for all SMT assembly and solder process.

Available on tape and reel.

Moisture sensitivity level: Level 3.

RoHS compliant.



### 1.3 Application

Ultraviolet disinfection.

UV sterilization.

Air purification.

General use.

## 1.4 Package Dimension

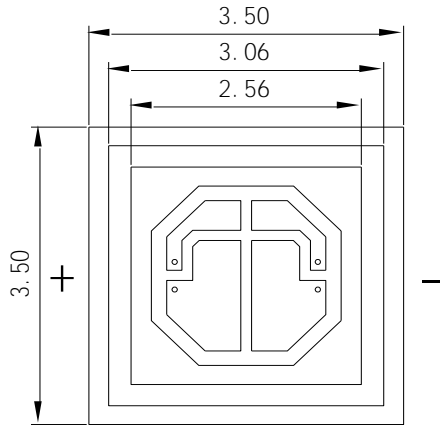


Fig.1-1 Top view

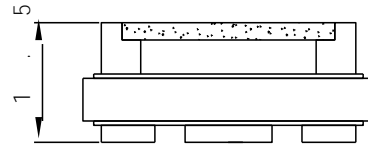


Fig.1-2 Side view

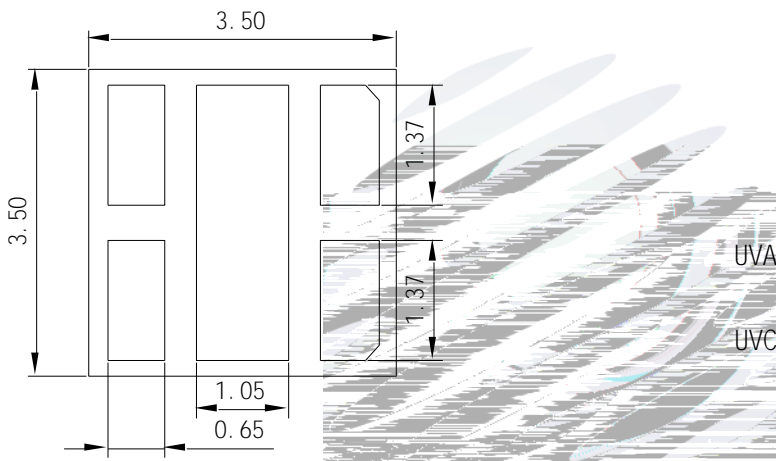


Fig.1-3 Bottom view

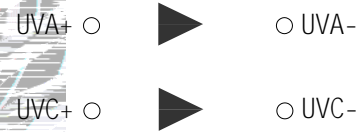


Fig.1-4 Polarity

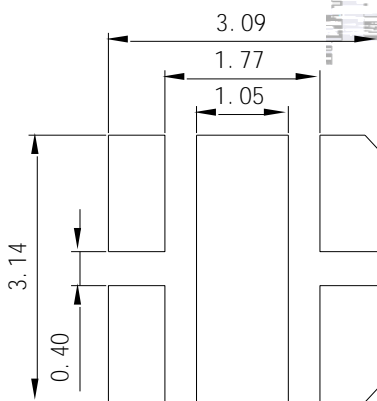


Fig.1-5 Soldering patterns

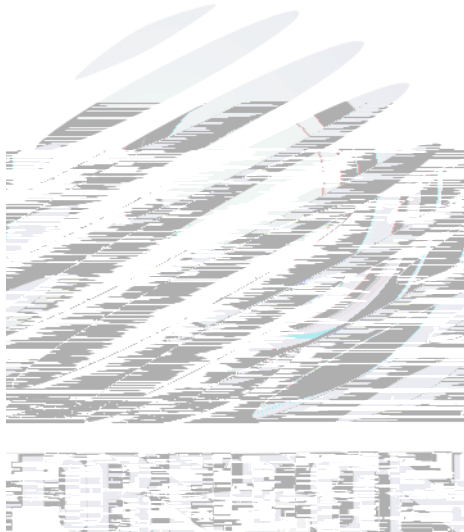
### Notes

All dimensions units are millimeters.

All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted.

cal / Optical Characteristics at Ts=25°C

Test Condition	Code	Value			Unit
		Min.	Typ	Max.	
I <sub>F</sub> =100mA	F02	4.5	---	5.5	V
	F03	5.5	6.2	6.5	
	F04	6.5	---	7.5	
I <sub>F</sub> =20mA	B11	3.0	---	3.2	
	B12	3.2	3.3	3.4	
	B13	3.4	---	3.6	
V <sub>R</sub> =10V	---	---	---	5	uA
I <sub>F</sub> =100mA	1J03	6	10	10	mW
	1J04	10	---	15	



## 1.6 Typical optical characteristics curves

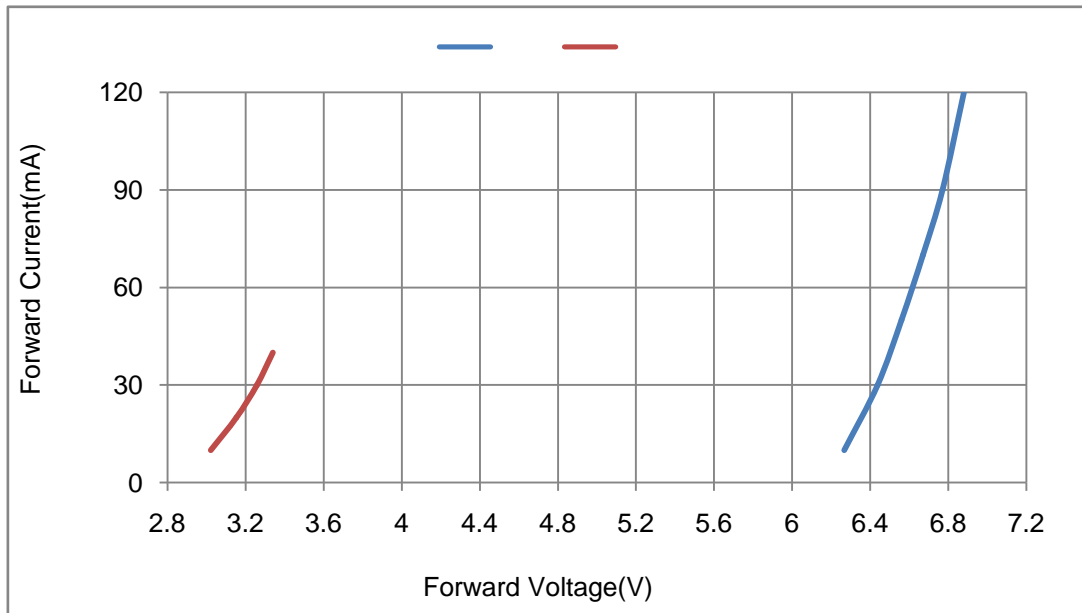


Fig.1- Forward Voltage Vs. Forward Current

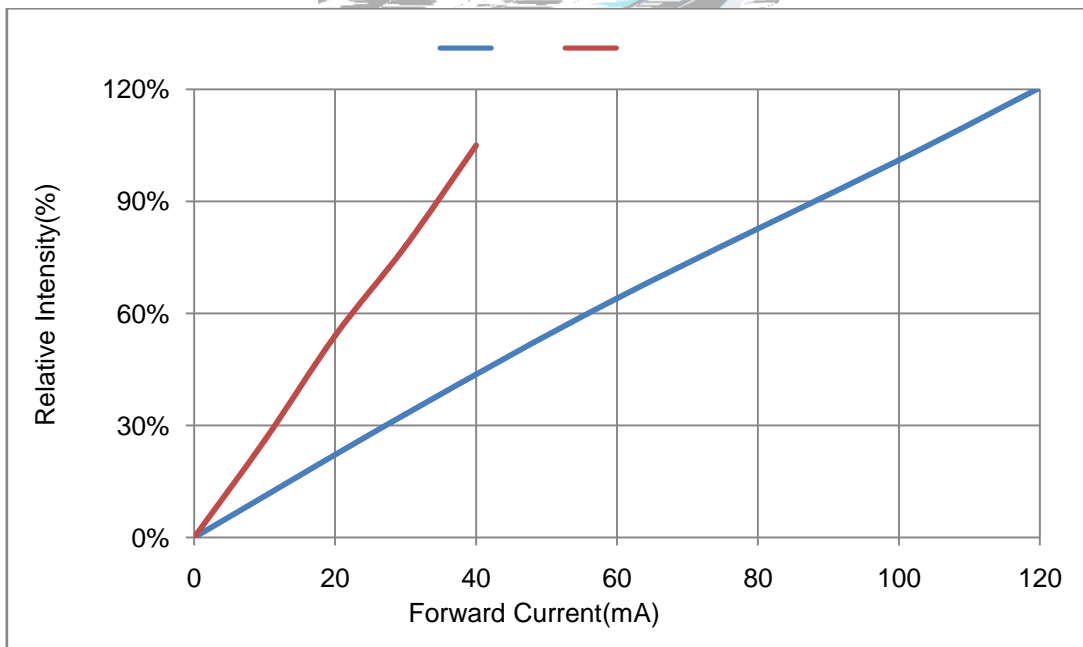
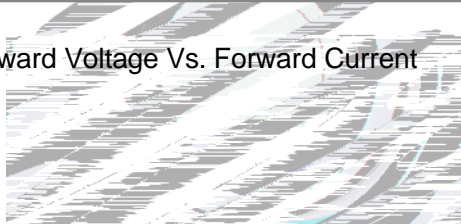


Fig.2- Forward Current Vs. Relative Power

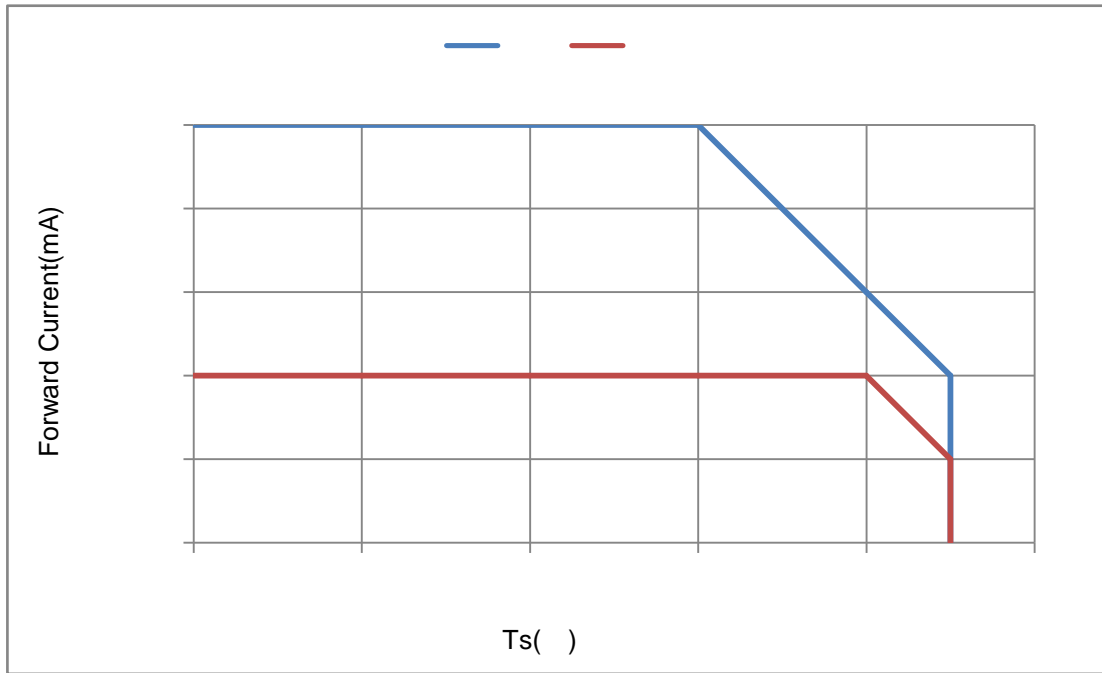


Fig.3-Ts Temperature VS. Forward Current

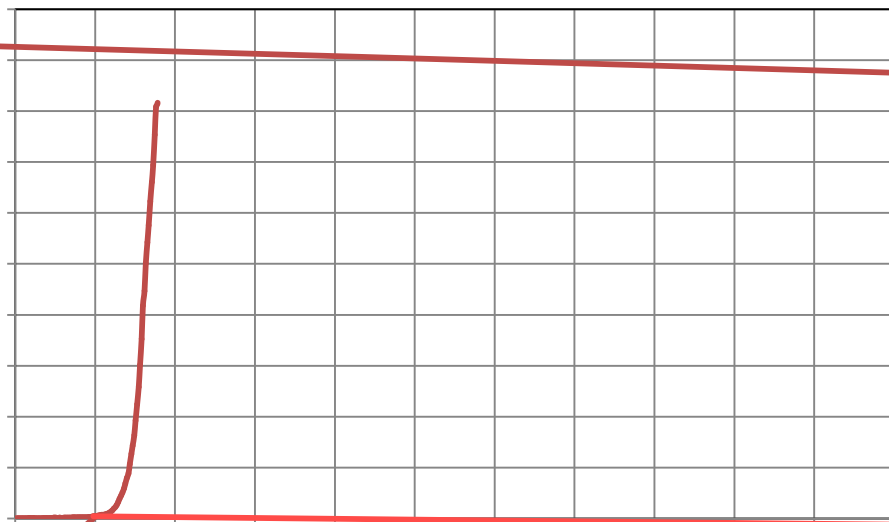


Fig.4-Spectrum Distribution



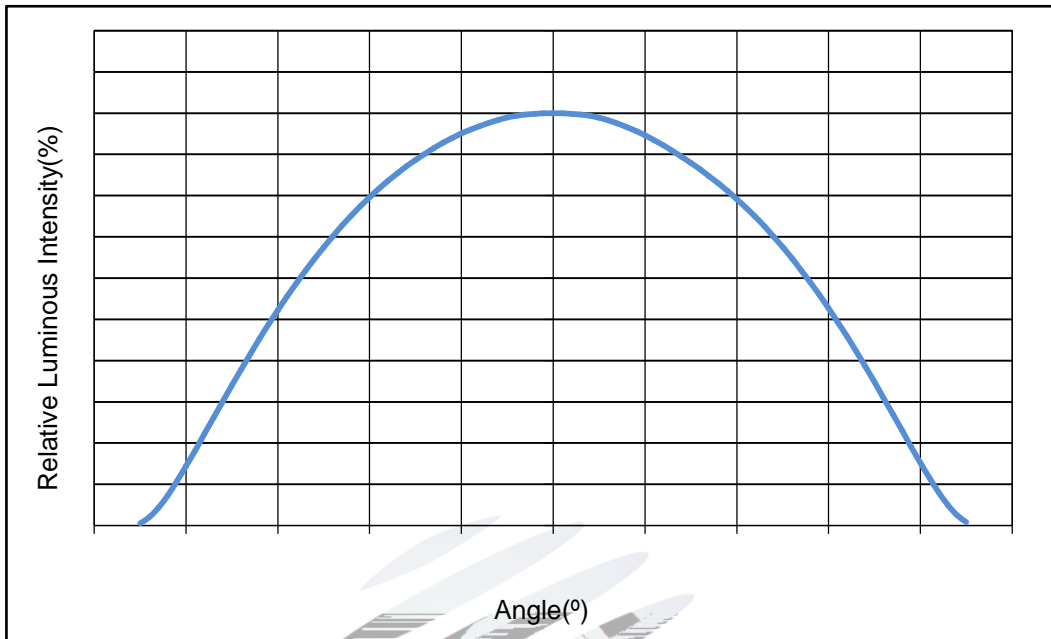
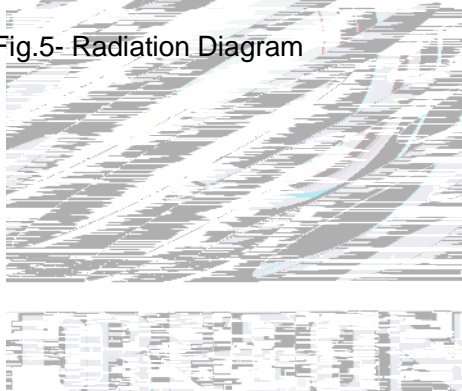


Fig.5- Radiation Diagram

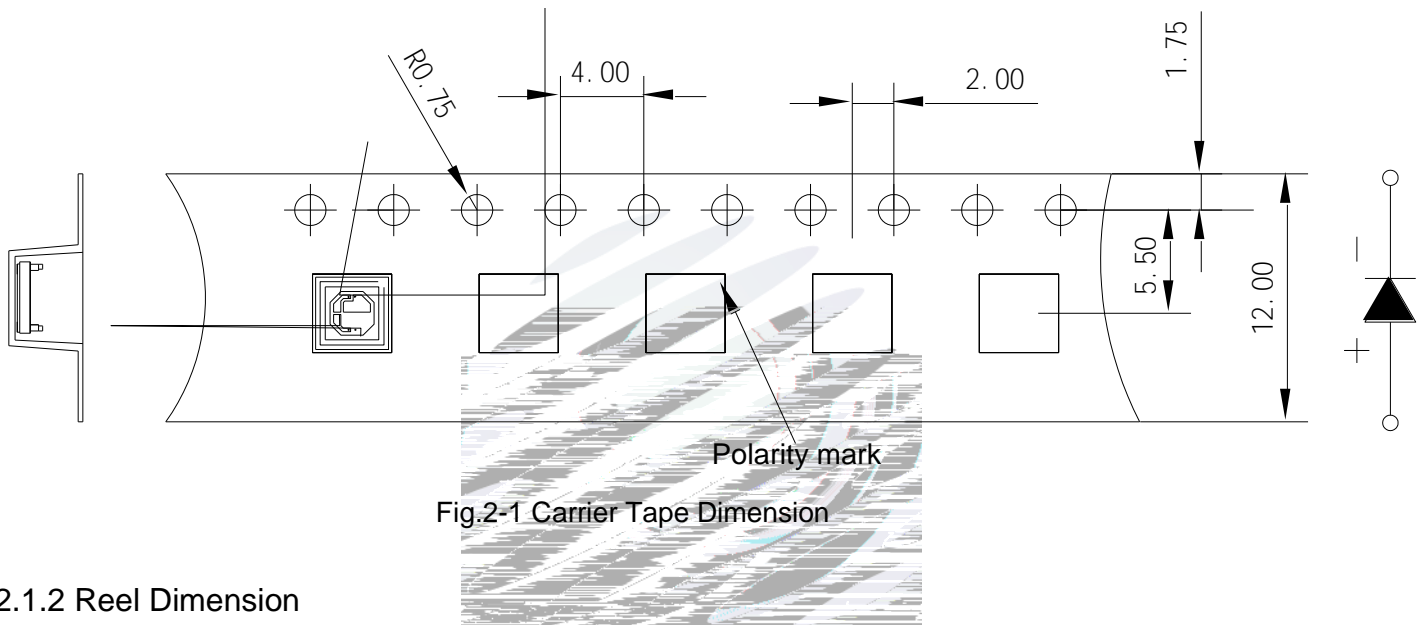


## 2. Packaging

### 2.1 Packaging Specification

Package:1000pcs/reel.

#### 2.1.1 Carrier Tape Dimension



#### 2.1.2 Reel Dimension

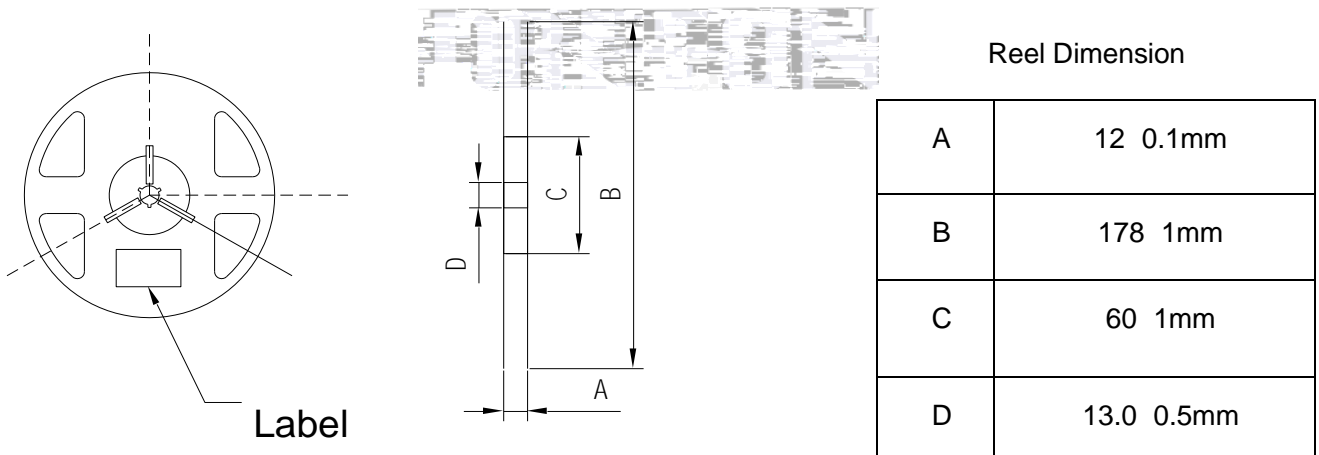


Fig.2-2 Reel Dimension

#### Notes

The tolerances unless mentioned  $\pm 0.1\text{mm}$ . Unit : mm

### 2.1.3 Label Form Specification

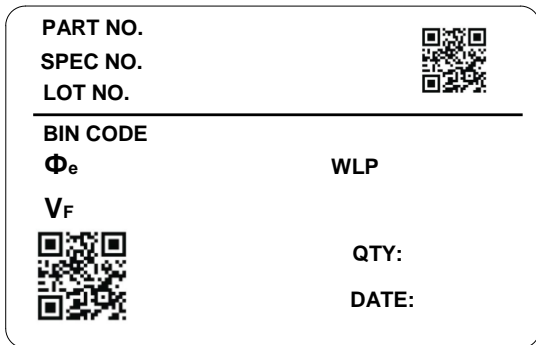


Fig. 2-3 Label Form Specification

#### Label Form Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
$\Phi_e$	Radiation flux
$V_F$	Forward Voltage
WLP	Wavelength
QTY	Packing Quantity
DATE	Made Date

### 2.2 Moisture Resistant Packing

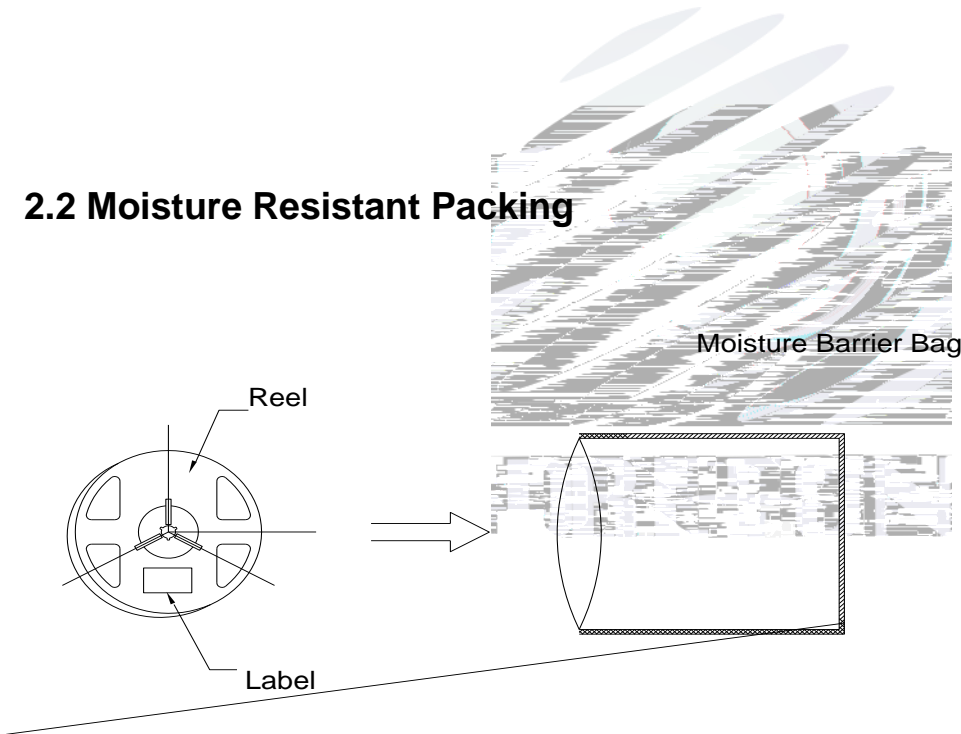


Fig.2-4 Moisture Resistant Packing Process

## 2.3 Cardboard Box

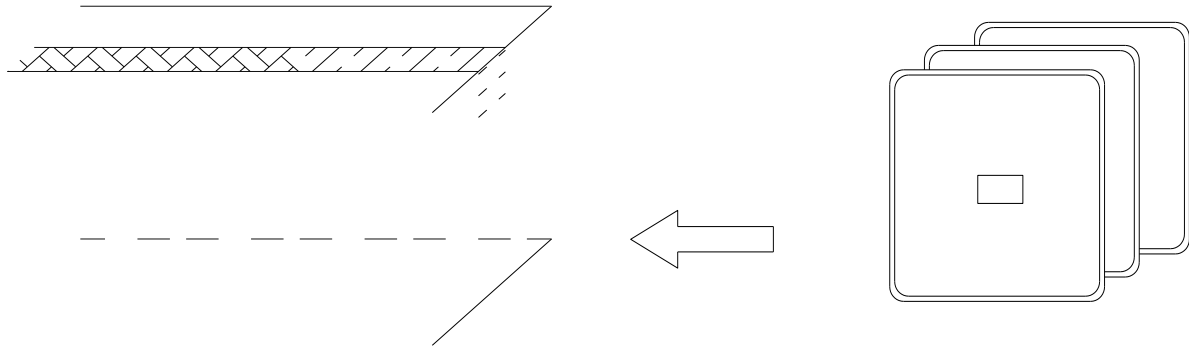


Fig.2-5 Cardboard Box

## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

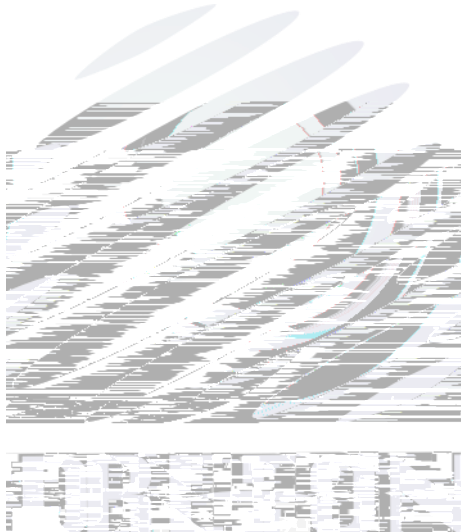
Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-B106	Temp:260 max T=10 sec	3times.	10Pcs.	0/1
Thermal Shock	JESD22-A106	-40 15min 100 15min	100 Cycles	10Pcs.	0/1
Life Test	JESD22-A108	T <sub>a</sub> =25 I <sub>F</sub> =20/100mA	1000Hrs.	10Pcs.	0/1

## 2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.

Forward Voltage





## Notes

(1) Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings, LED will be damaged.

(2) When soldering, do not put stress on the LEDs during heating.

### 3.1.1 Soldering Iron

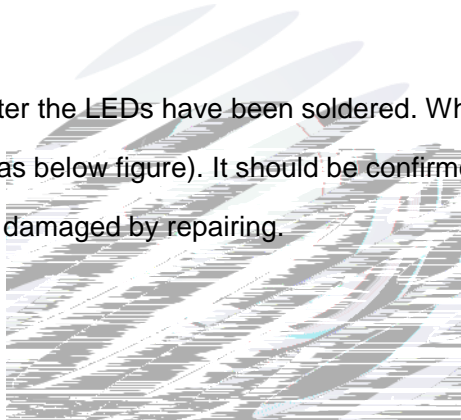
(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds.

(2) Soldering by hand should be done only one time.

### 3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED



### 3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

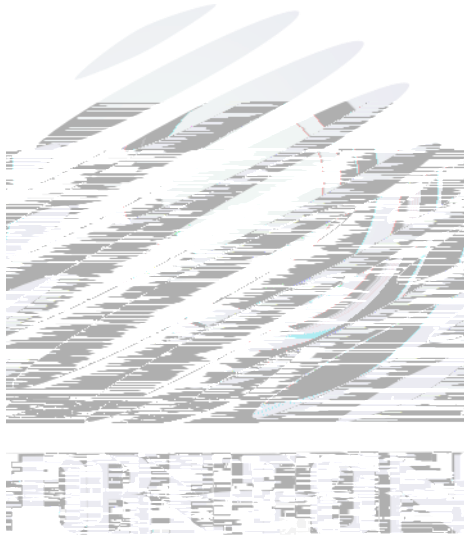




Fig 4-1 Operate Method

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for

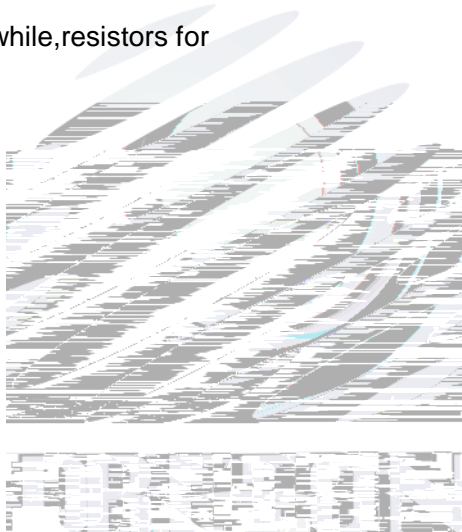
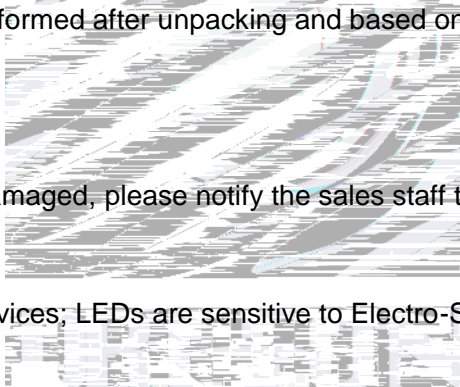


Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 65 5 for above 24 hours.



If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) When using this product, you need to take good care to prevent it from causing harm to eyes and human body.

(11) Other points for attention, please refer to our relevant information.

